

DPX1326E

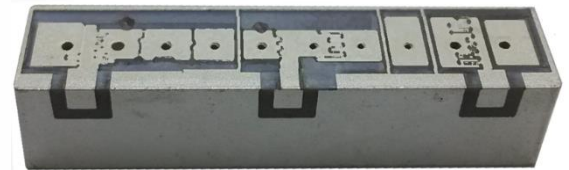
Band 12+13 vs 5/26 DPX Series Diplexer

Features

- Extended version of DPX1326A with support to 915MHz
- Frequency combining of closely spaced frequency bands
- Superior power handling and reliability
- Universal footprint across all DPX series products

Applications

- Wireless Infrastructure applications
- Multi-band Pico Cells, Femto-cells, Repeaters and indoor DAS systems for up to 1.0W/band at the antenna port.



Part Dimensions: 31.7 × 8.1 × 7.6 mm • 9.8 g
Materials: Ag plated ceramic block

Description

Surface mount ceramic diplexer supports a universal footprint across all DPX series products enabling the use of a common system PCB. Provides superior rejection, insertion loss, reliability, and power handling.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	3.0 Watt max
Peak Input Power	-	-	-	30 Watt max

Low-Band to Antenna Response

Passband Insertion Loss (5 MHz avg)	698-757	0.6 dB	0.7 dB max	0.8 dB max
	776-787	1.1 dB	1.3 dB min	1.4 dB min
Passband Return Loss	698-787	11 dB	10 dB min	10 dB min
Attenuation:	814-849	22 dB	20 dB min	20 dB min
	859-915	35 dB	25dB min	25 dB min

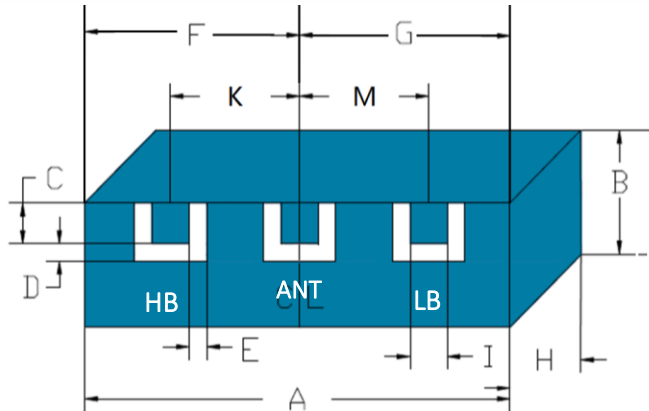
High-Band to Antenna Response

Passband Insertion Loss (5 MHz avg)	814-817	1.2 dB	1.4 dB max	1.5 dB max
	817-824	1.1 dB	1.3 dB min	1.4 dB min
	824-849	0.9 dB	1.1 dB max	1.2 dB max
	859-915	0.6 dB	0.8 dB max	1.0 dB max
Passband Return Loss	814-915	11 dB	10 dB min	10 dB min
Attenuation:	698-757	32 dB	25 dB min	25 dB min
	776-787	25 dB	20 dB min	20 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

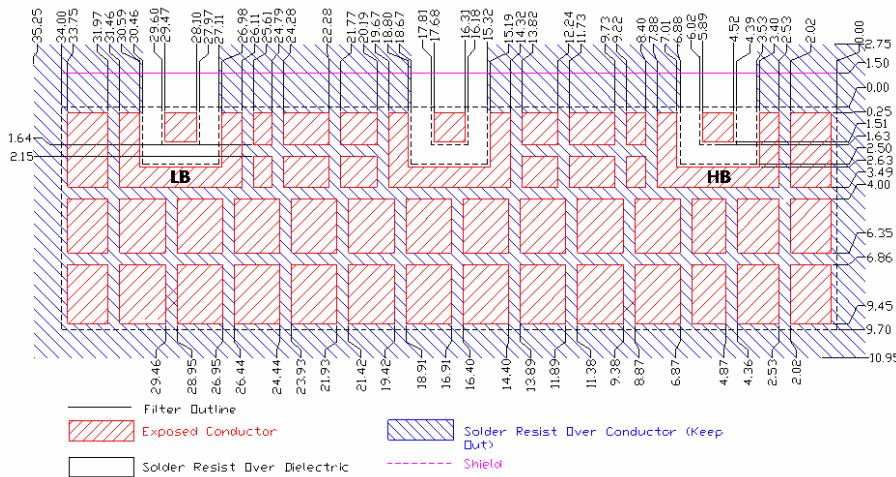
Specification Allowance	
Insertion Loss	0.1 dB
Return Loss	1.0 dB
Attenuation	1.0 dB

Mechanical Drawing



Dim.	Nominal (mm)	Tolerance (±mm or Max)
A	31.67	Max
B	8.10	Max
C	1.63	0.13
D	0.86	0.13
E	0.86	0.13
F	15.84	0.13
G	15.84	0.13
H	7.60	Max
I	1.63	0.13
K	11.79	0.13
M	11.79	0.13

PCB Layout



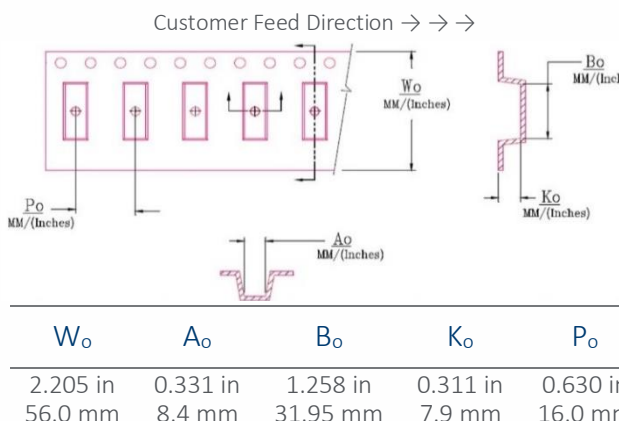
IMPORTANT: Please assure ≥ 20 mils (0.5mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the required ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow incl. 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking

Dimension	Units	Spec.	Product Marking
Reel Diameter	mm	330	CTS
Reel Weight	kg	3.8	326E
Reel Quantity	ea.	250	YWW



Electrical Response

